

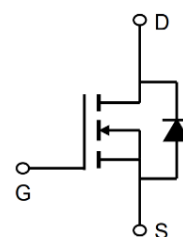
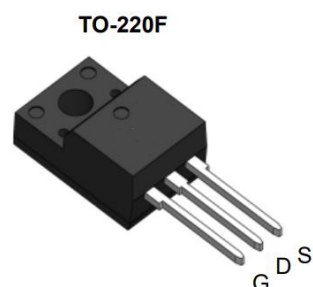
650V N-Channel Enhancement Mode MOSFET

General Features

V_{DS}	I_D	$R_{DS(ON)}$ Type @ $V_{GS}=10V$
650V	10A	0.82 Ω

Description

The VSMP10N65F is silicon N -channel Enhanced VDMOSFETs, is obtained by the self-aligned planar Technology which reduce the conduction loss, improve switching performance and enhance the avalanche energy. The transistor can be used in various power switching circuit for system miniaturization and higher efficiency.



Application

Uninterruptible Power Supply(UPS)

Power Factor Correction (PFC)

Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
VSMP10N65F	TO-220F-3L	VSM P10N65F XXXX YYYY	1000

Absolute Maximum Ratings ($T_c=25^{\circ}C$ unless otherwise noted)

Symbol	Parameter	Value	Unit
V_{DSS}	Drain-Source Voltage ($V_{GS} = 0V$)	650	V
I_D	Continuous Drain Current	10	A
I_{DM}	Pulsed Drain Current (note1)	58	A
V_{GS}	Gate-Source Voltage	± 30	V
E_{AS}	Single Pulse Avalanche Energy (note2)	426	mJ
I_{AR}	Avalanche Current (note1)	9	A
E_{AR}	Repetitive Avalanche Energy note1)	41	mJ
P_D	Power Dissipation ($T_c = 25^{\circ}C$)	32.1	W
T_J, T_{stg}	Operating Junction and Storage Temperature Range	$-55 \sim +150$	$^{\circ}C$
R_{thJC}	Thermal Resistance, Junction-to-Case	4.46	$^{\circ}C/W$
R_{thJA}	Thermal Resistance, Junction-to-Ambient	46.7	$^{\circ}C/W$

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Electrical Characteristics (T_J=25°C, unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
V(BR)DSS	Drain-Source Breakdown Voltage	V _{GS} = 0V, I _D = 250μA	650	685	--	V
IDSS	Zero Gate Voltage Drain Current	V _{DS} = 650V, V _{GS} = 0V, T _J = 25°C	--	--	1	μA
IGSS	Gate-Source Leakage	V _{GS} = ±30V	--	--	±100	nA
VGS(th)	Gate-Source Threshold Voltage	V _{DS} = V _{GS} , I _D = 250μA	2.0	--	4.0	V
RDS(on)	Drain-Source On-Resistance (Note3)	V _{GS} = 10V, I _D = 3.5A	--	0.82	0.95	Ω
Ciss	Input Capacitance	V _{GS} = 0V, V _{DS} = 25V, f = 1.0MHz	--	1037	--	pF
Coss	Output Capacitance		--	138	--	
Crss	Reverse Transfer Capacitance		--	5.3	--	
Qg	Total Gate Charge	V _{DD} = 520V, I _D = 9A, V _{GS} = 10V	--	19	--	nC
Qgs	Gate-Source Charge		--	7.3	--	
Qgd	Gate-Drain Charge		--	8.5	--	
td(on)	Turn-on Delay Time	V _{DD} = 325V, I _D = 7A, R _G = 25Ω	--	18	--	ns
t _r	Turn-on Rise Time		--	30	--	
td(off)	Turn-off Delay Time		--	61	--	
t _f	Turn-off Fall Time		--	36	--	
IS	Continuous Body Diode Current	T _C = 25 °C	--	--	9.0	A
ISM	Pulsed Diode Forward Current		--	--	36	A
VSD	Body Diode Voltage	T _J = 25°C, I _{SD} = 7A, V _{GS} = 0V	--	--	1.2	V
trr	Reverse Recovery Time	V _{GS} = 0V, I _S = 7A, di _F /dt = 100A/μs	--	431	--	ns
Qrr	Reverse Recovery Charge		--	2.6	--	μC

Note :

- 1、 The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2、 The EAS data shows Max. rating . IAS = 9.0A, VDD = 50V, RG = 25 Ω, Starting T_J = 25 °C
- 3、 The test condition is Pulse Test: Pulse width ≤ 300μs, Duty Cycle ≤ 1%
- 4、 The power dissipation is limited by 150°C junction temperature
- 5、 The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.

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Typical Characteristics

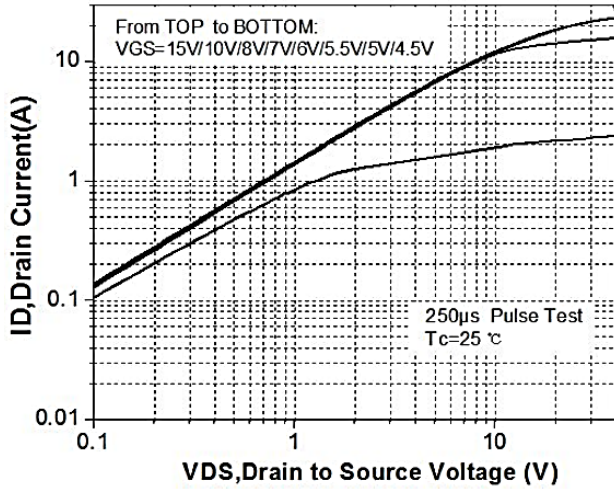


Figure 1. On-Region Characteristics

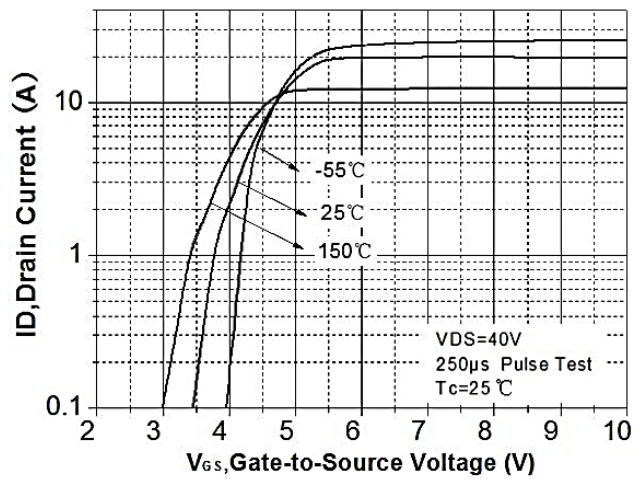


Figure 2. Transfer Characteristics

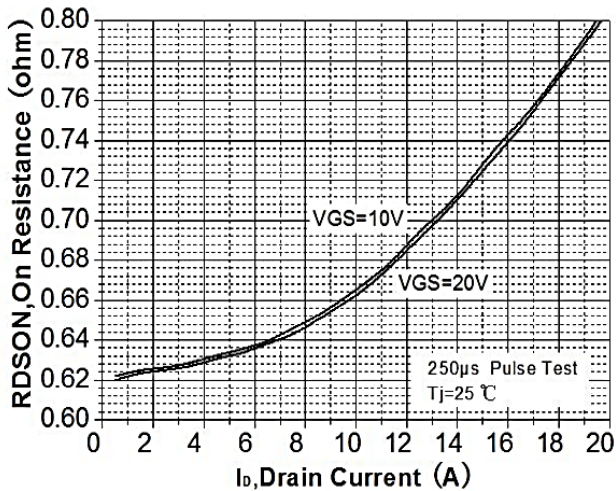


Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage

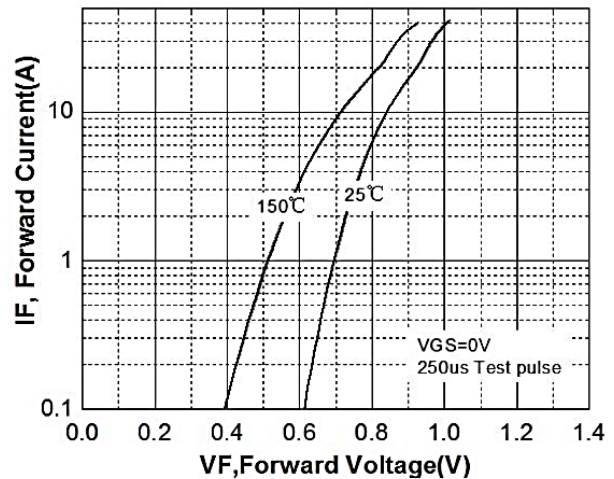


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

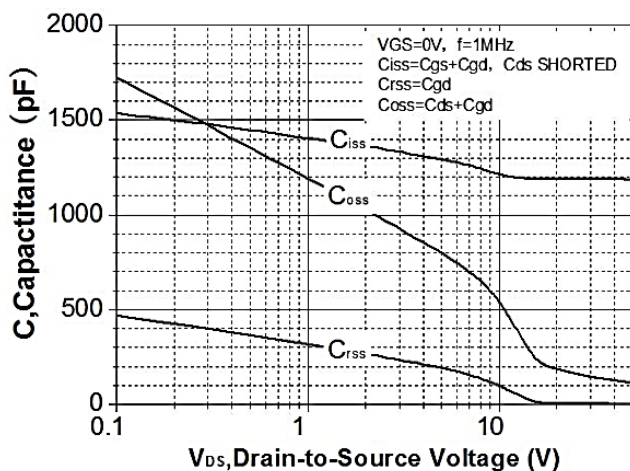


Figure 5. Capacitance Characteristics

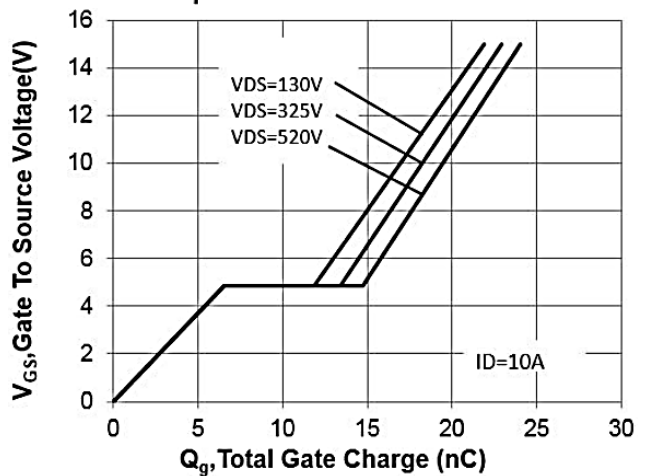
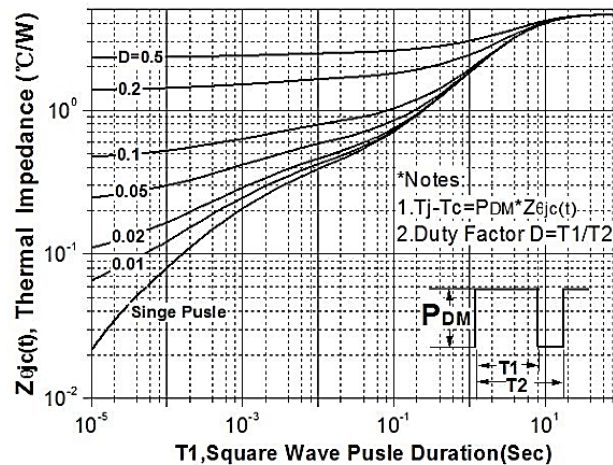
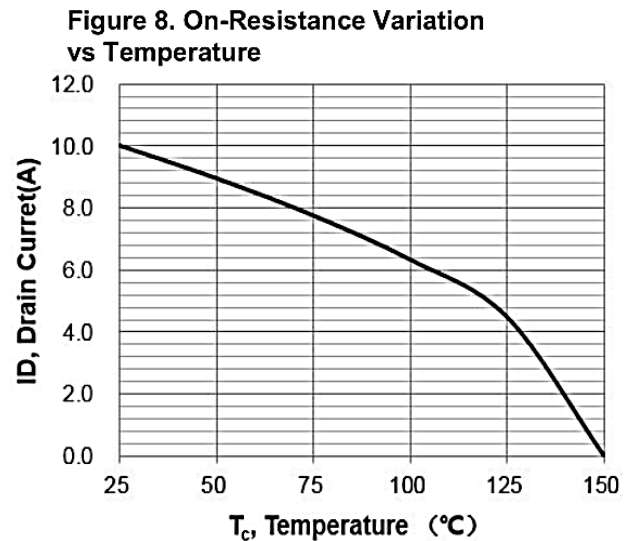
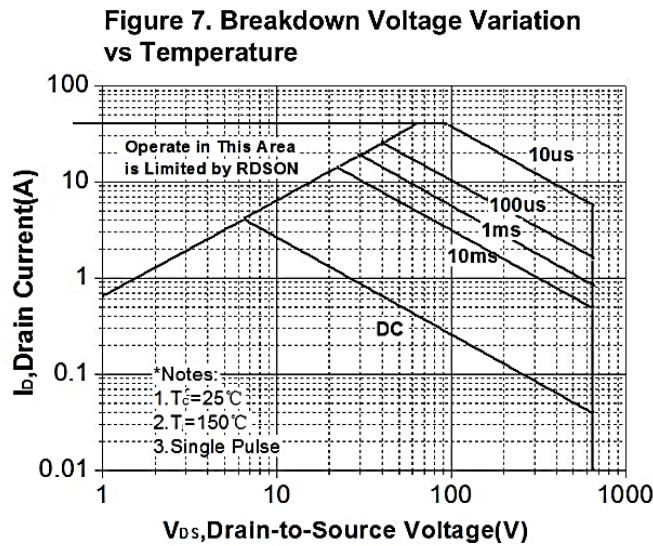
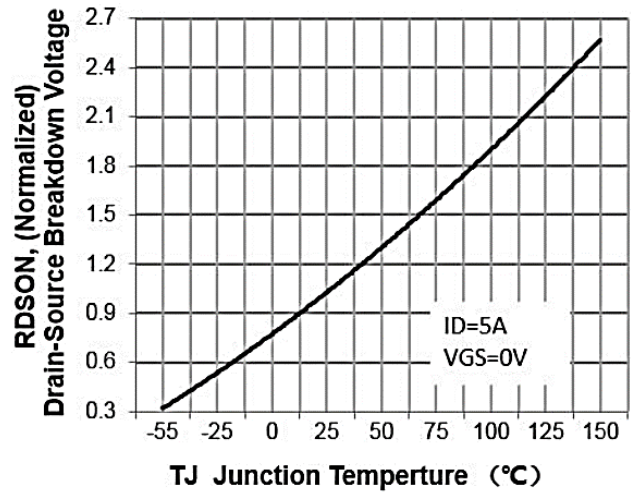
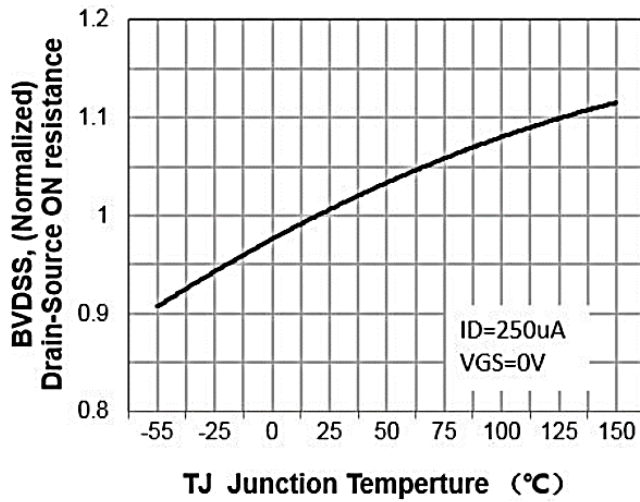


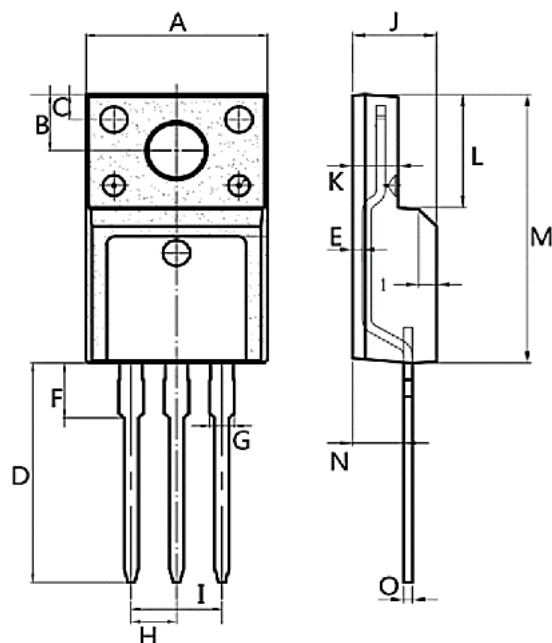
Figure 6. Gate Charge Characteristics

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Package Mechanical Data-TO-220F-3L



Symbol	Common	
	mm	
	Mim	Max
A	9.9	10.3
B	2.9	3.5
C	1.15	1.45
D	12.75	13.25
E	0.55	0.75
F	3.1	3.5
G	1.25	1.45
H	2.54	
I	5.08	
J	4.55	4.75
K	2.4	2.7
L	6.35	6.75
M	15.0	16.0
N	2.75	3.15
O	0.45	0.60